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# Eureka1/2 S.LSI Rev0.7

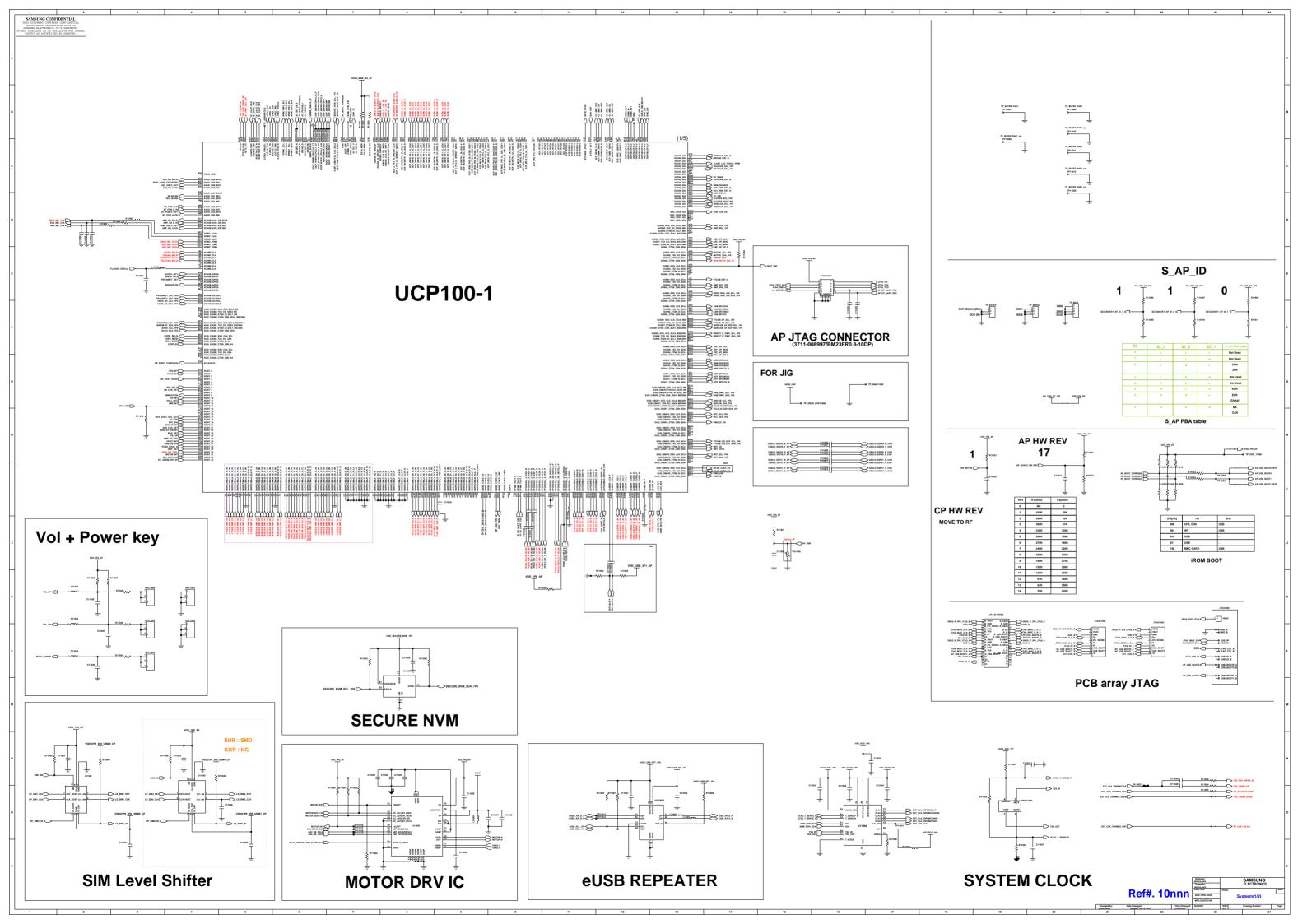
SM-S921B

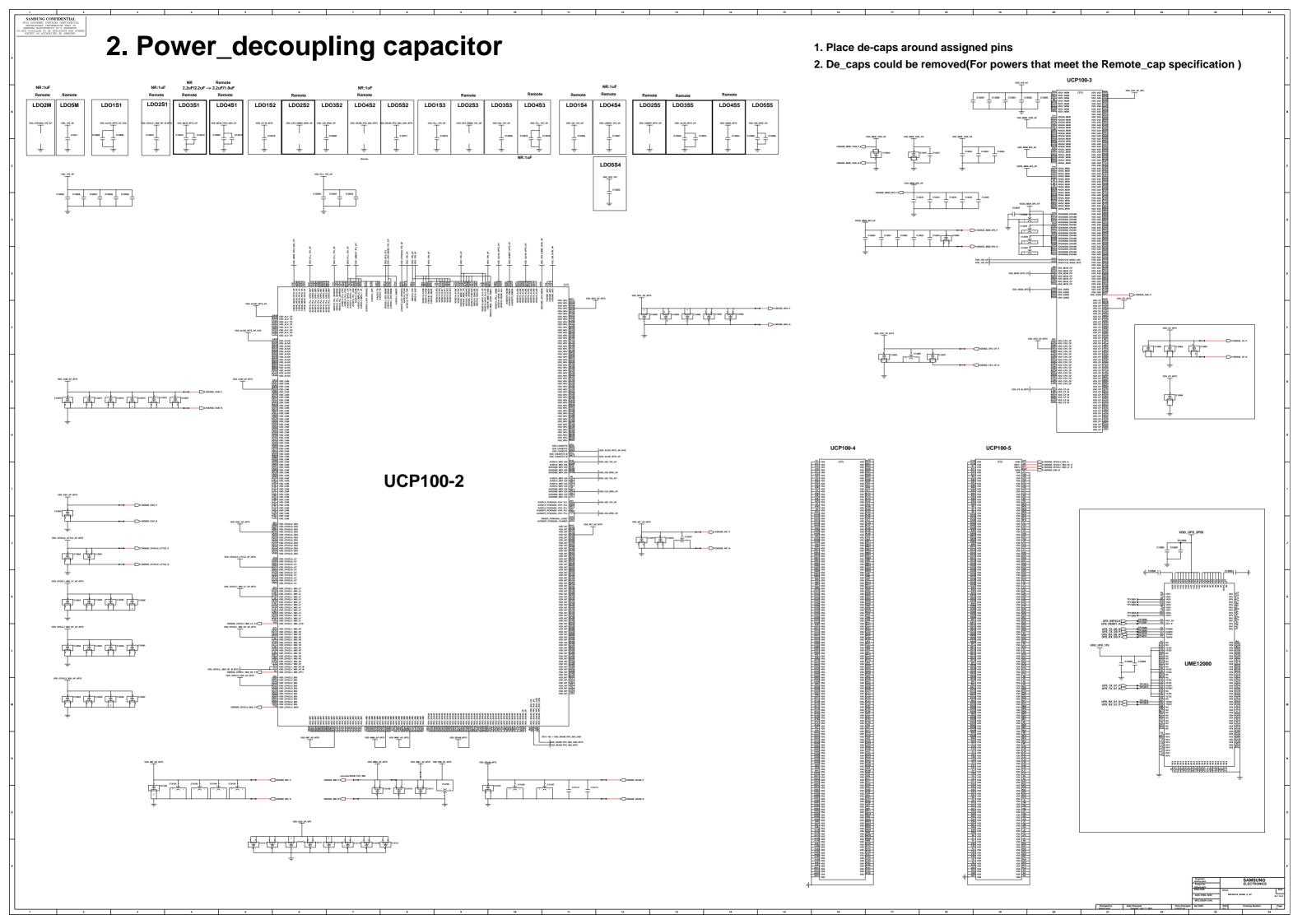
**S\_AP PCB part** 

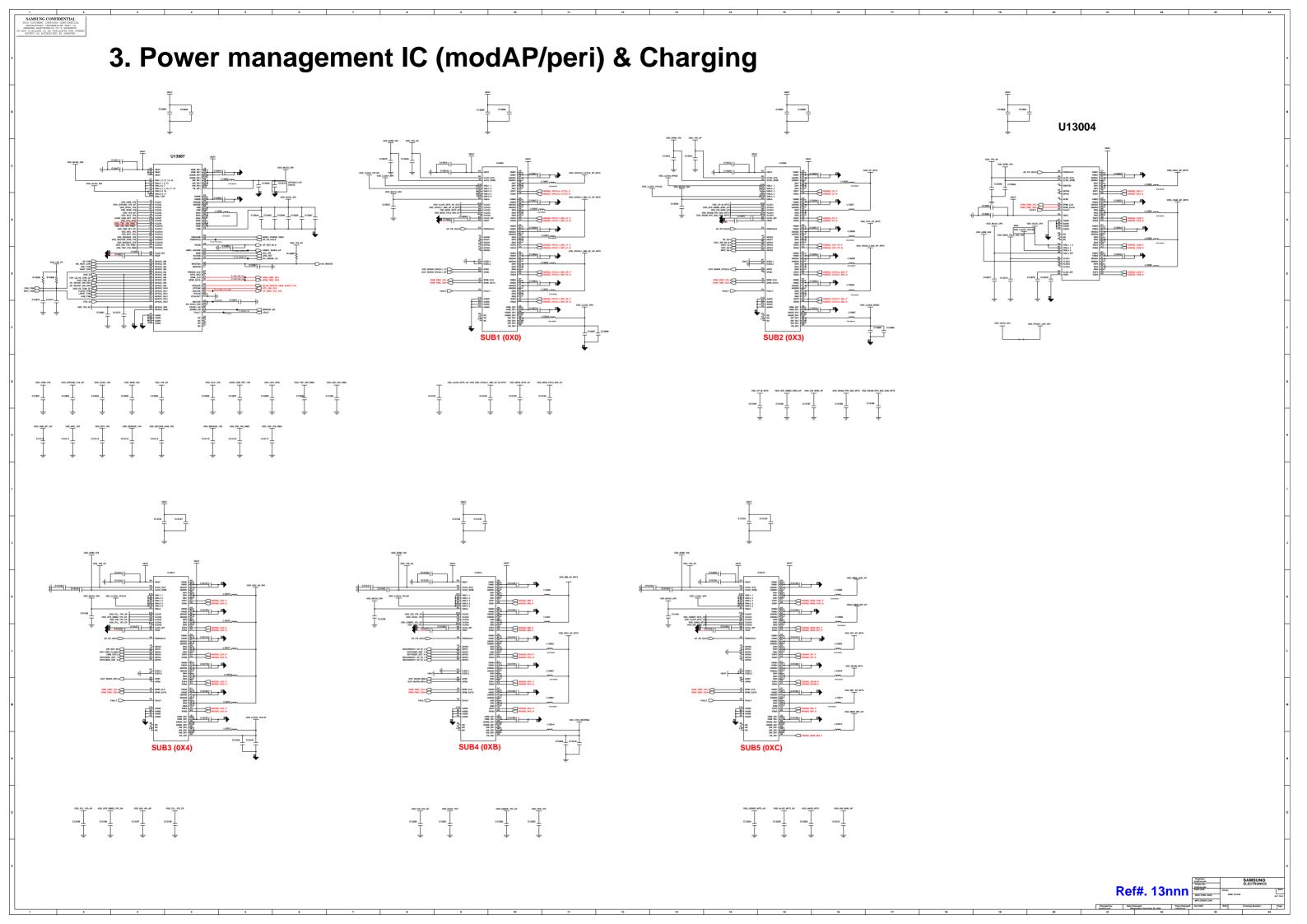
2023.09.27

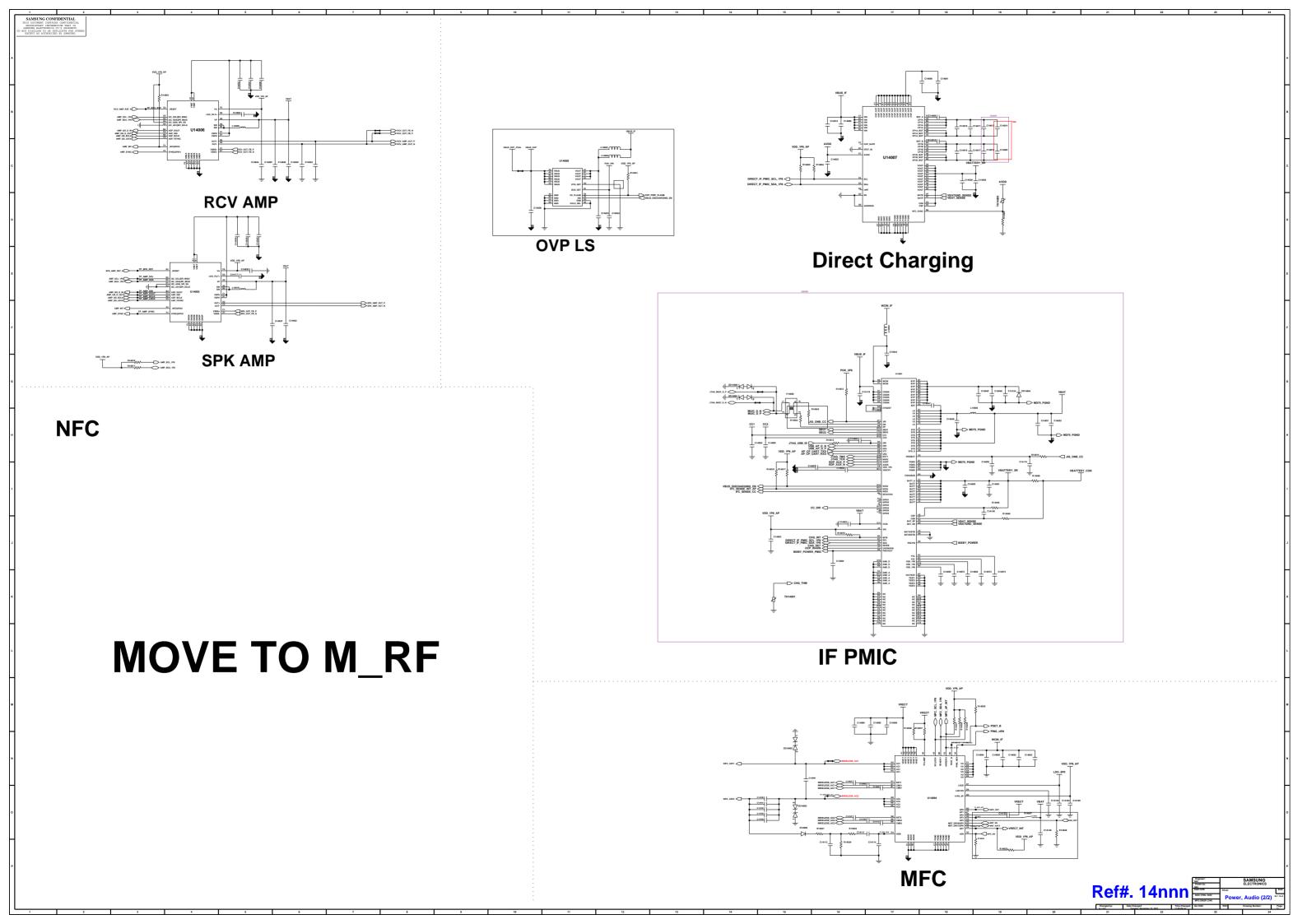
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Ref#.	11nnn	12nnn	13nnn	14nnn	15nnn	16nnn	17nnn	18nnn	19nnn	10nnn
Contents	AP IO AP Associated Motor Driver JTAG Key FPCB PCB ID	AP Power decap UFS memory	Core PMIC group	Audio AMP Charger MFC	RF Ant. UHB ET MOD#3	RF PMIC	UWB	CAM PMIC Wide CAM Tele 3x CAM		Interposer Shieldcan Bosshole
sheet	sheet01	sheet02	sheet03	sheet04	sheet05	sheet06	sheet07	sheet08	sheet09	sheet10

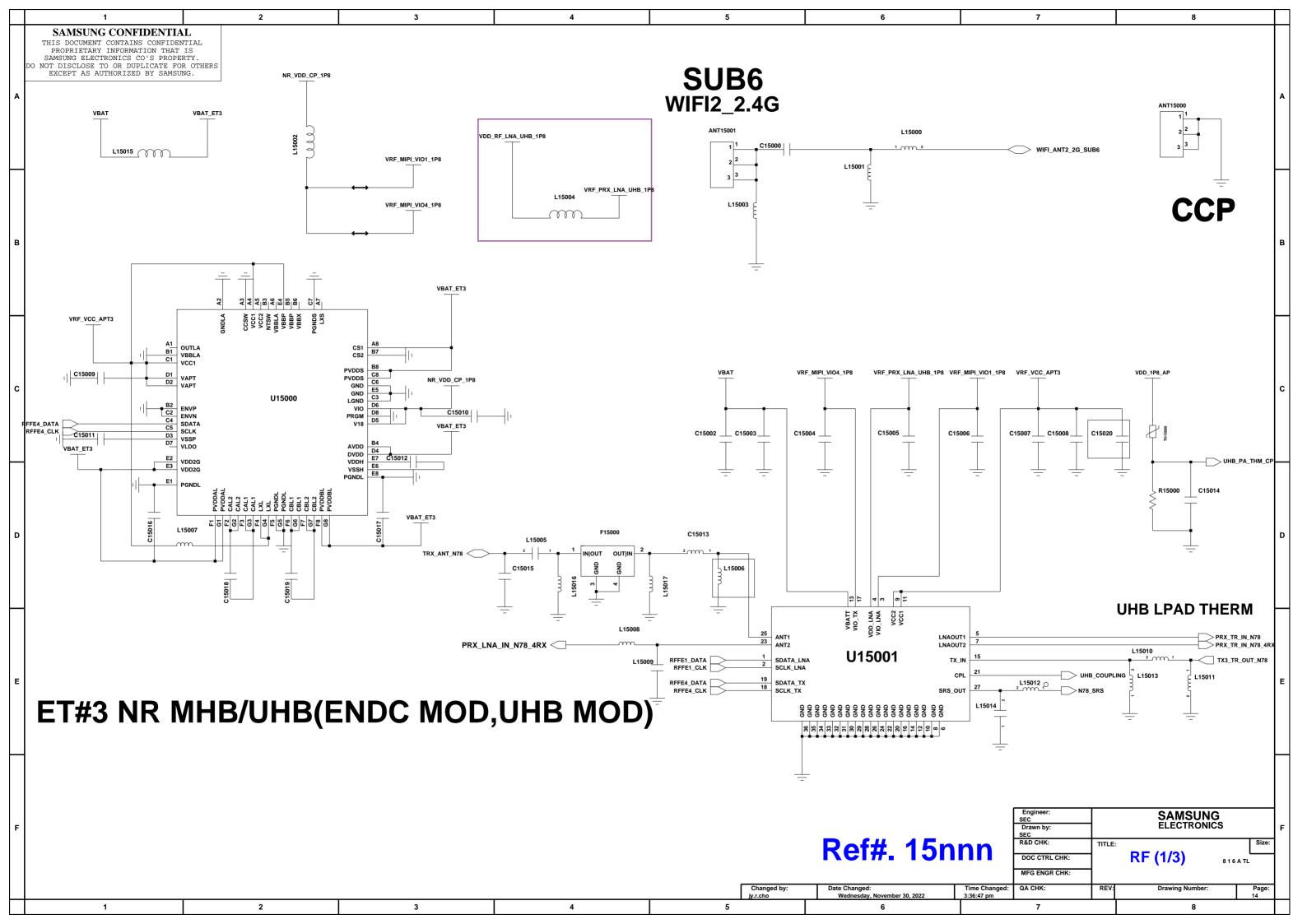
Engineer: SEC
DITATE by: SEC
DITATE by: SEC
TITLE:
DOC CRECHIC:
M/SENGR CHIC:
M/SENGR CHIC:
REV
Drawing Number:



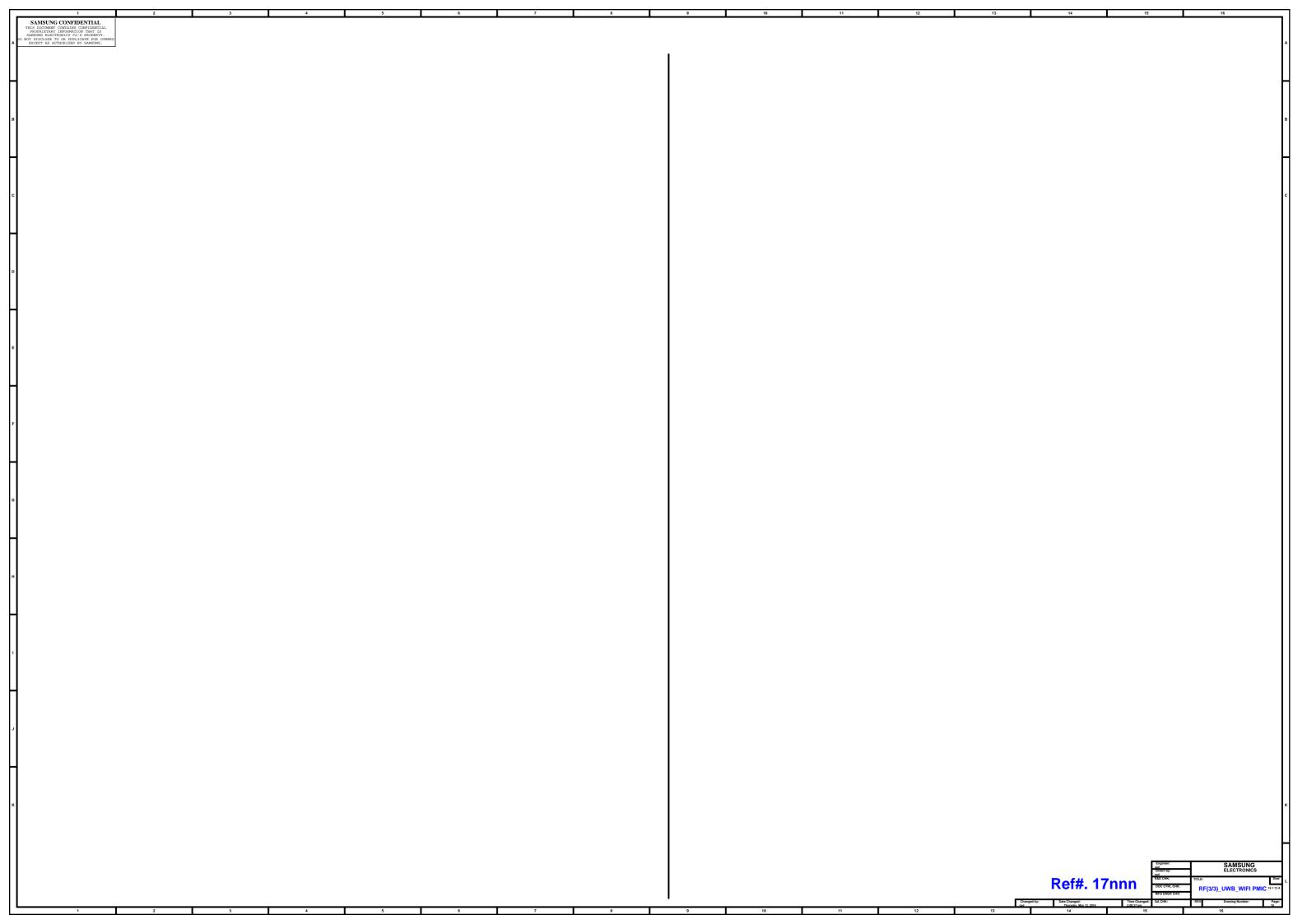


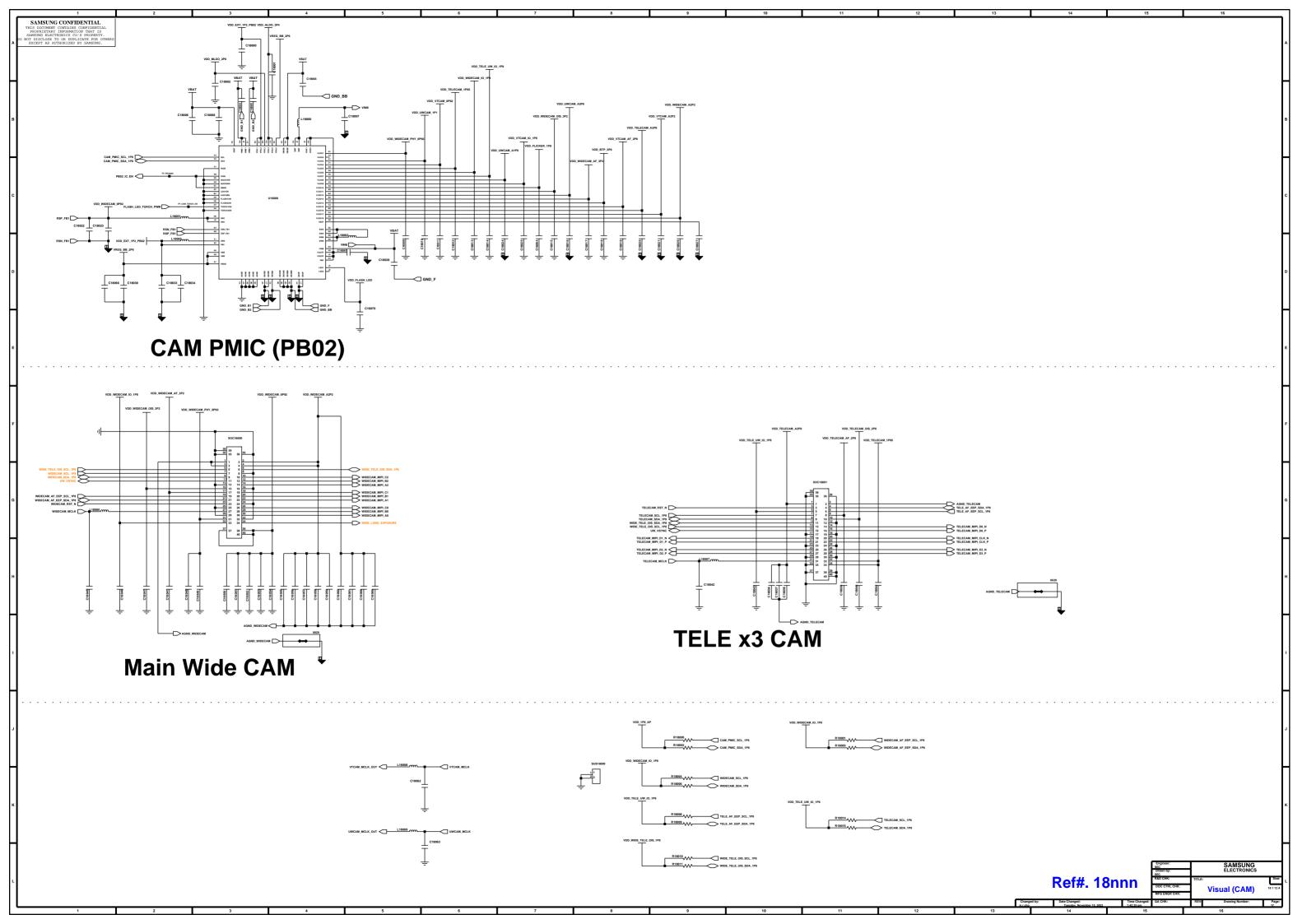


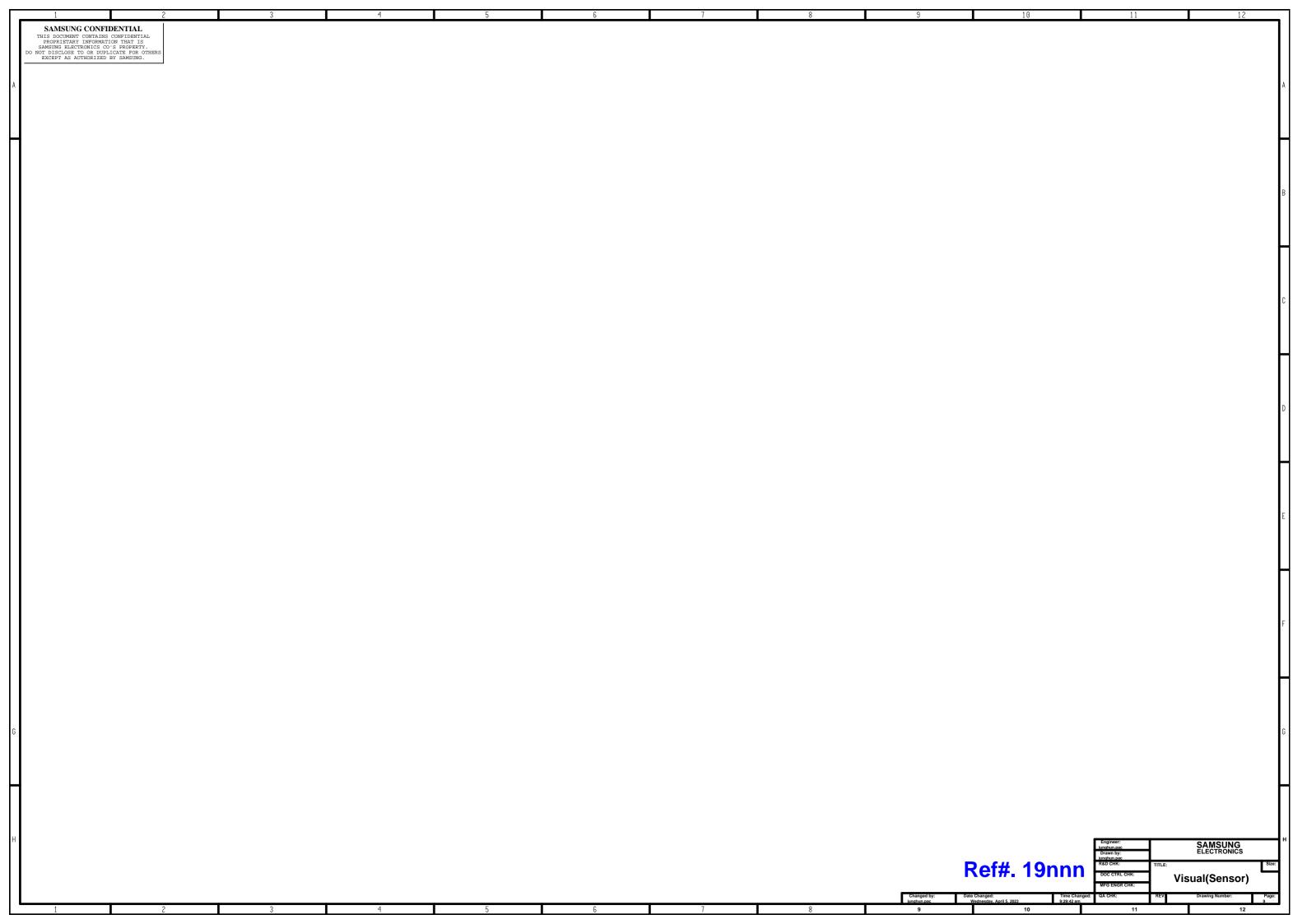




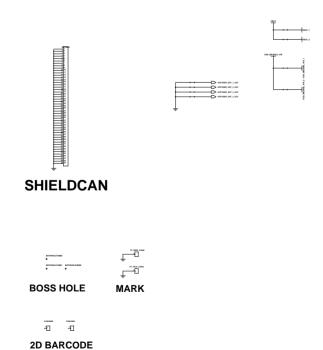
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EXCEPT AS AUTHORIZED BY SAMSING **RF PMIC** U16000 Ref#. 16nnn

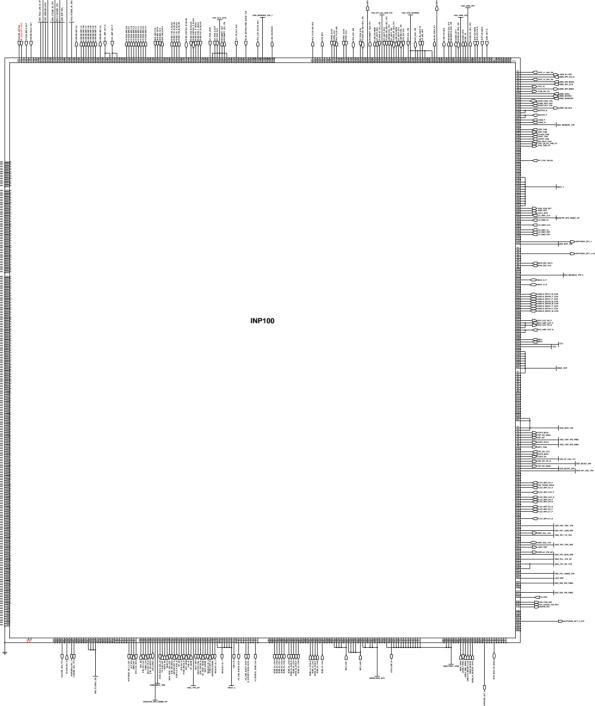


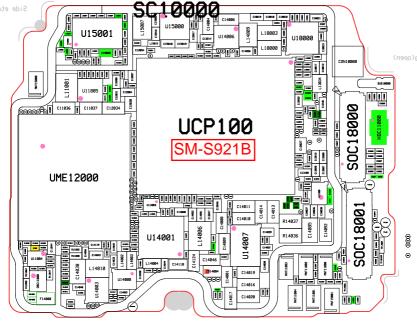


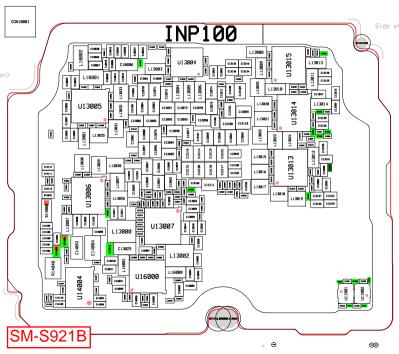


# INTERPOSER Design









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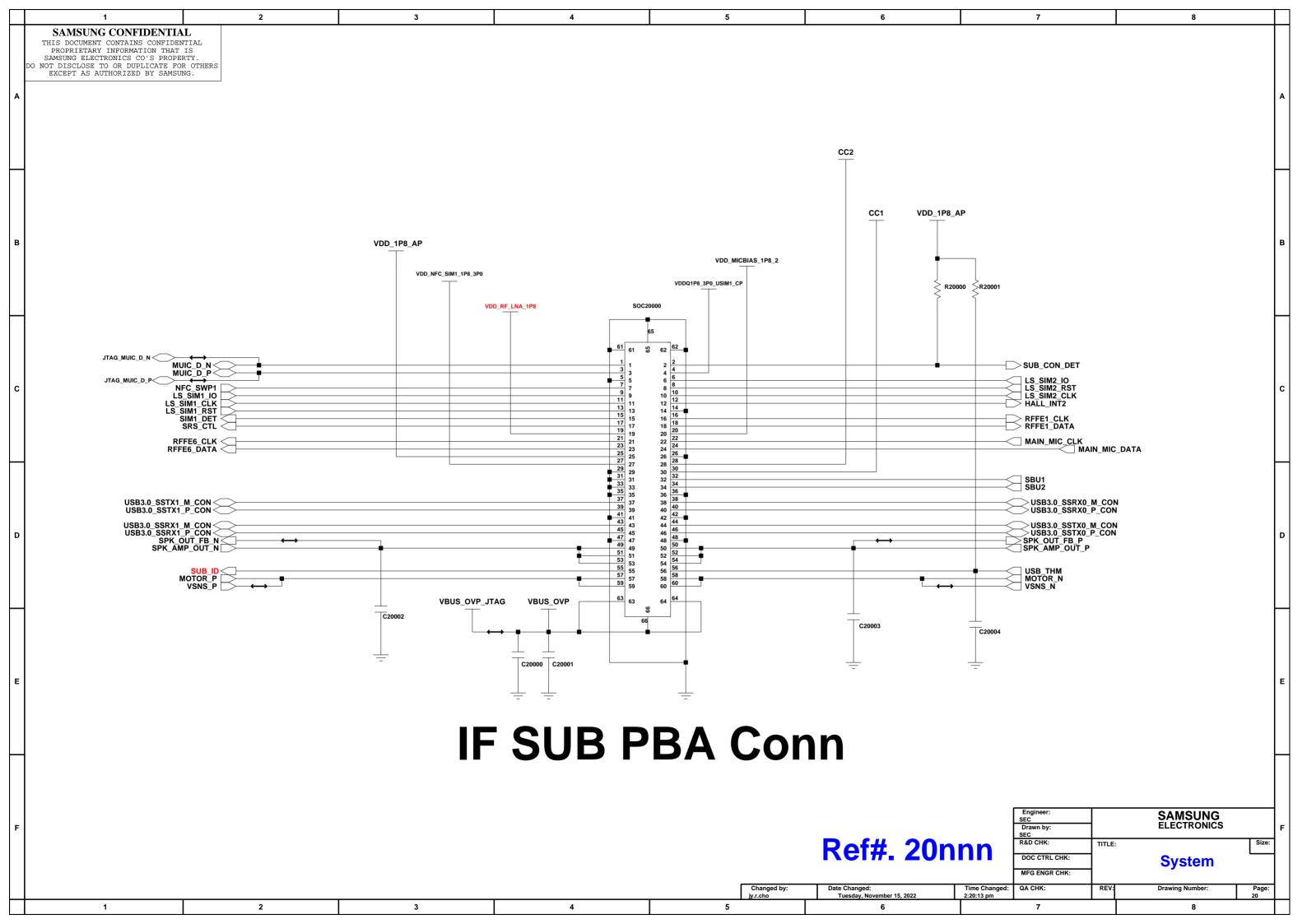
# **SM-S921B\_M\_RF\_REV0.7**

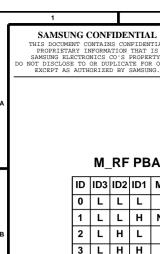
SM-S921B

2023. 10.04

TG	Sys	tem		wer dio	RF			Visual (CAM)	VIsual (Disp.) VIsual (Sensor)	HW Structure
Ref#.	20nnn	21nnn	22nnn	23nnn	24nnn	25nnn	26nnn	27nnn	28nnn	29nnn
	IF Sub PBA	PCB ID	BATT conn.	Audio AMP	ANT	LPAMID	BT/WiFi	Flash	Sensor	Interposer
		JTAG	DCM leakage	2nd/3rd MIC	mmW ANT	TRCV	GPS	Ranging	Display PMIC	Shieldcan
			WPC conn.	RCV cont.	LFEM	RF PMIC	UWB	UWCAM	Display conn.	
Contents						QET		VTCAM	Digitizer	
									PROXIMITY Sensor	
			WPC							
			WFC							
sheet	sheet01	sheet02	sheet03	sheet04	sheet05	sheet06	sheet07	sheet08	sheet09	sheet10

Engineer:
Diswn by:
RAD CHR:
DOC CTRL CHR:
WE GRAN CHR:
AMO GRAN CHR:
AMO GRAN CHR:
AMO GRAN CHR:
AMO GRAN CHR:
Among C. GA CHK:
REV. Drawing Number:

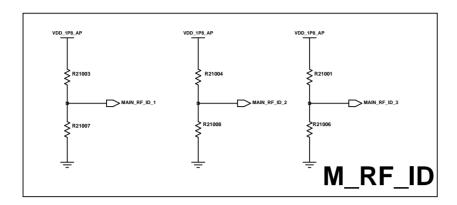


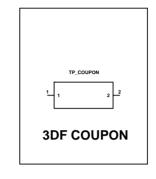


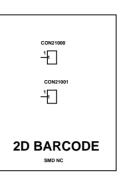
# **ETC PART**

### M\_RF PBA table

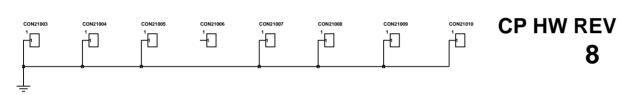
ID	ID3	ID2	ID1	M_RF PBA type		
0	L	L	L	NA_mmW		
1	L	L	Н	NA_CAN_Sub6		
2	L	Н	L	CHN_SUB6		
3	L	Н	Н	Global_SUB6		
4	Н	L	L	JPN_mmW		
5	Н	L	Н	KOR_SUB6		
6	Н	Н	L	EUR_SUB6		
7	Н	Н	Н	N/A		

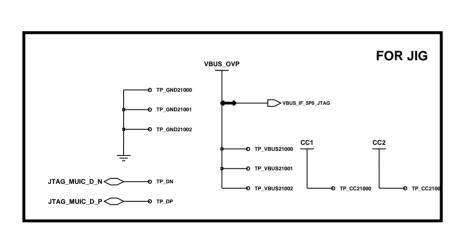


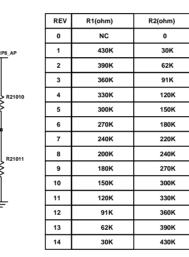




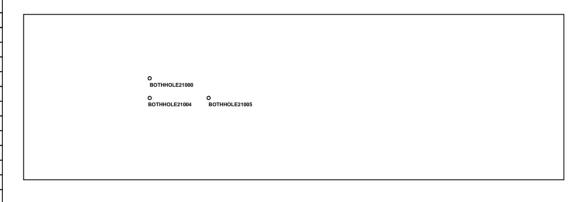


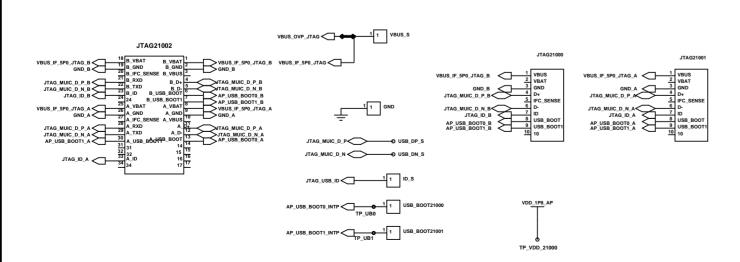




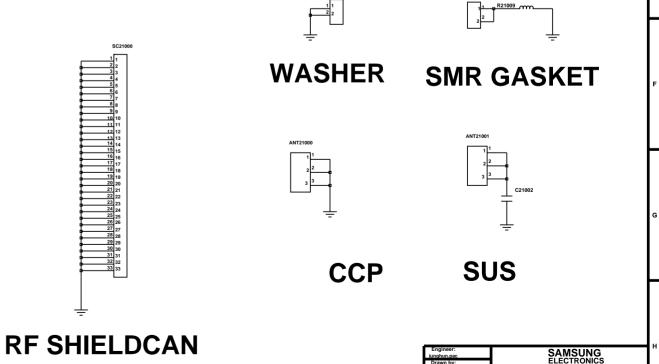


### **Boss Hole**



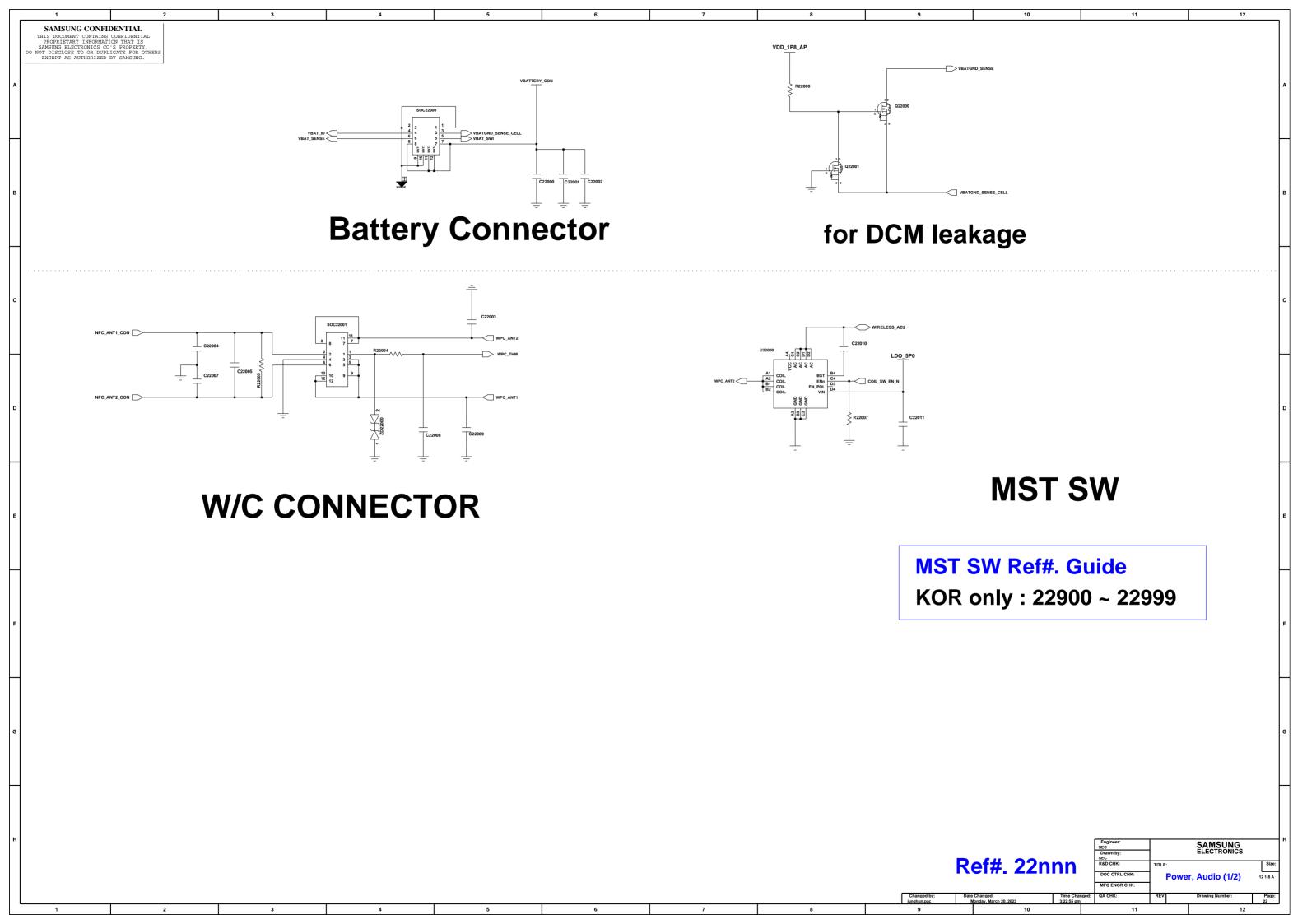


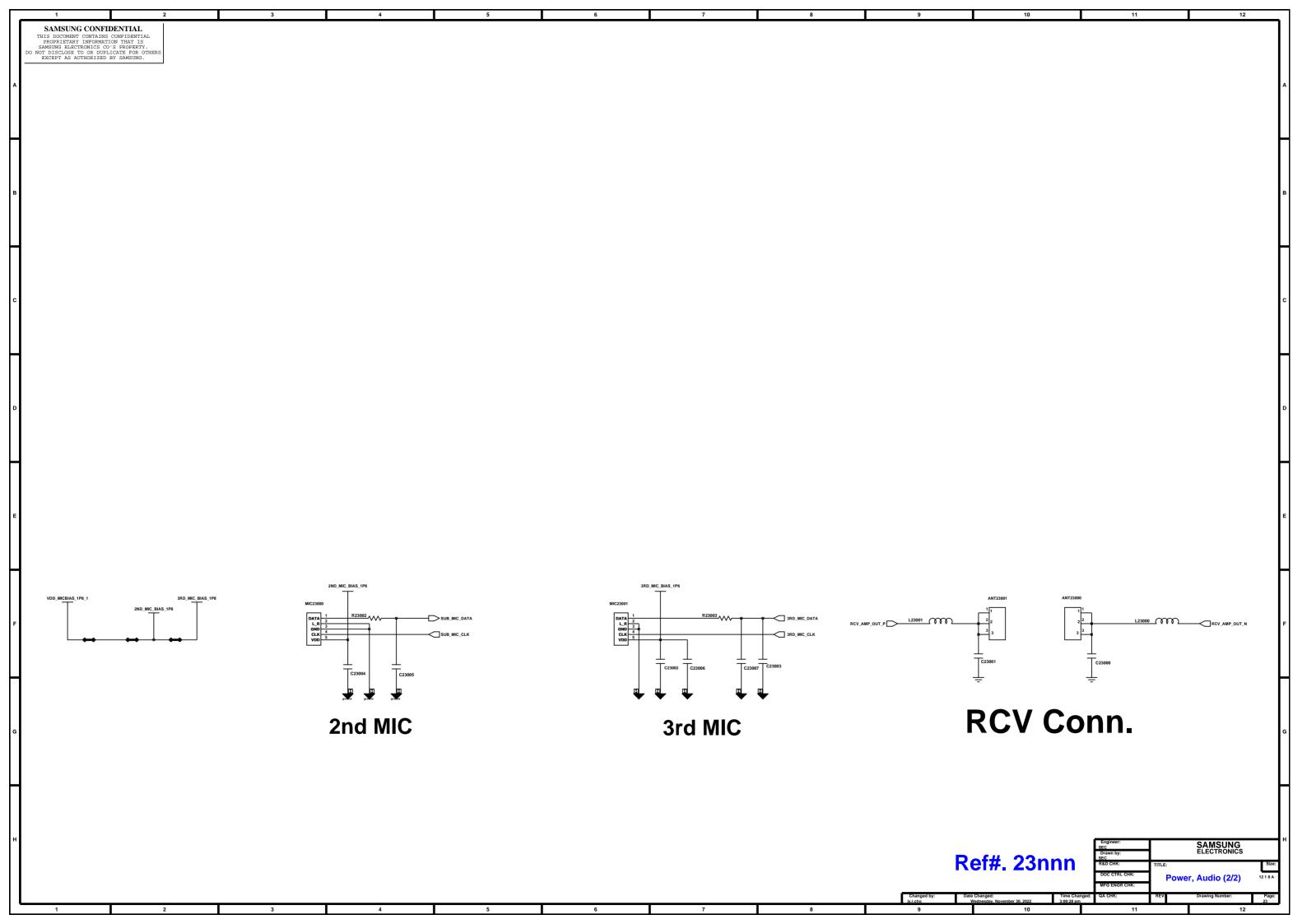
**PCB** array JTAG

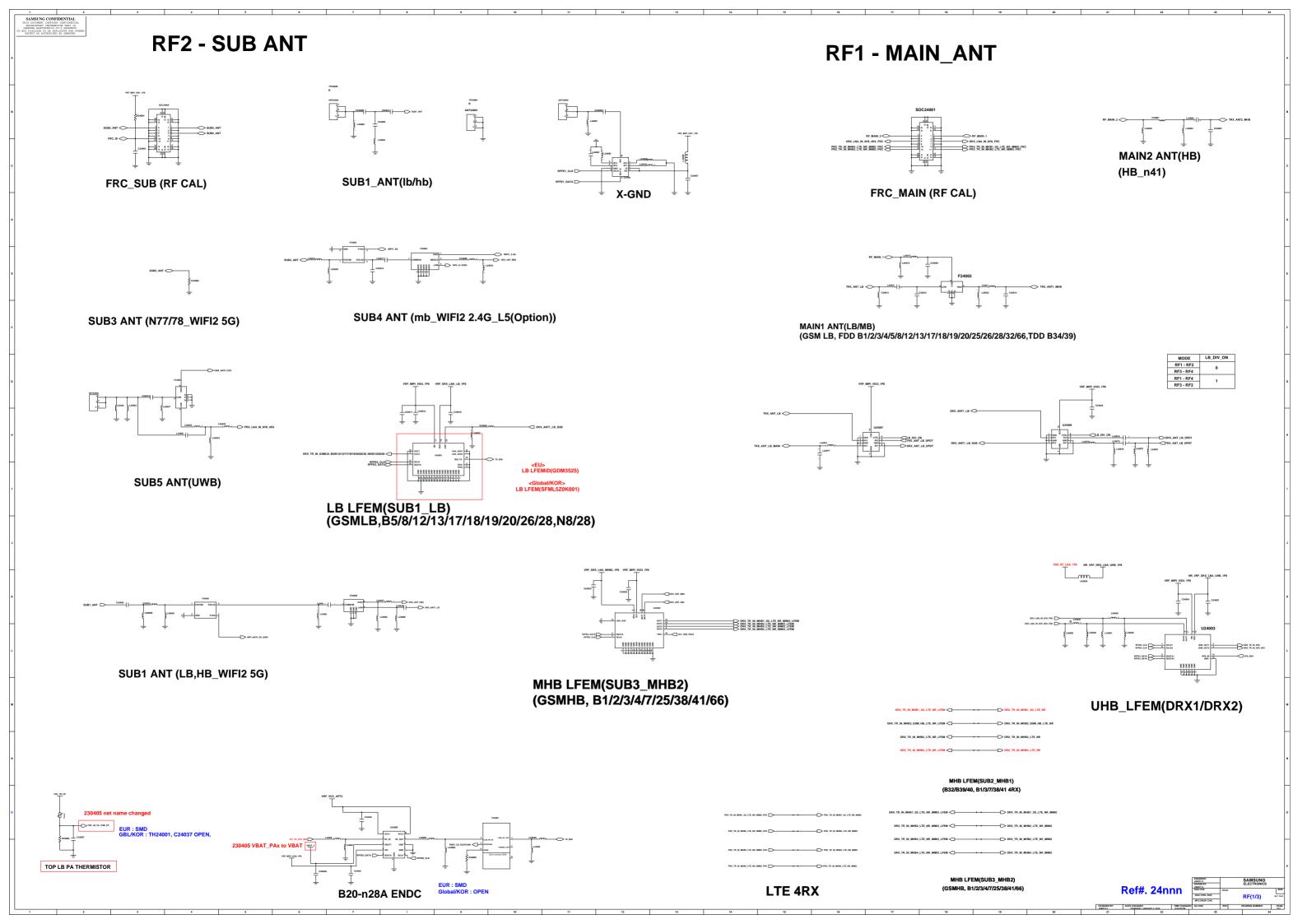


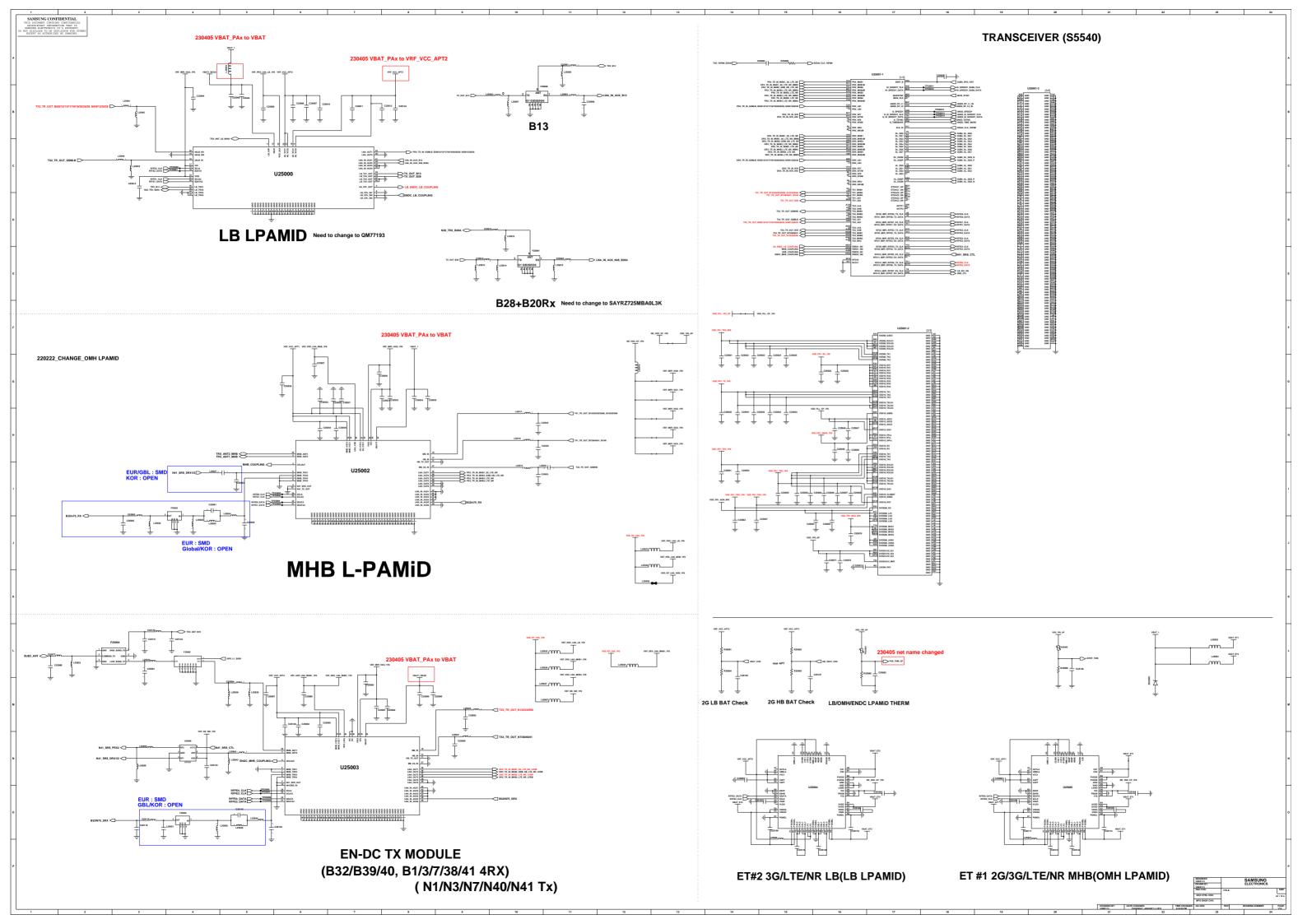
Ref#. 21nnn

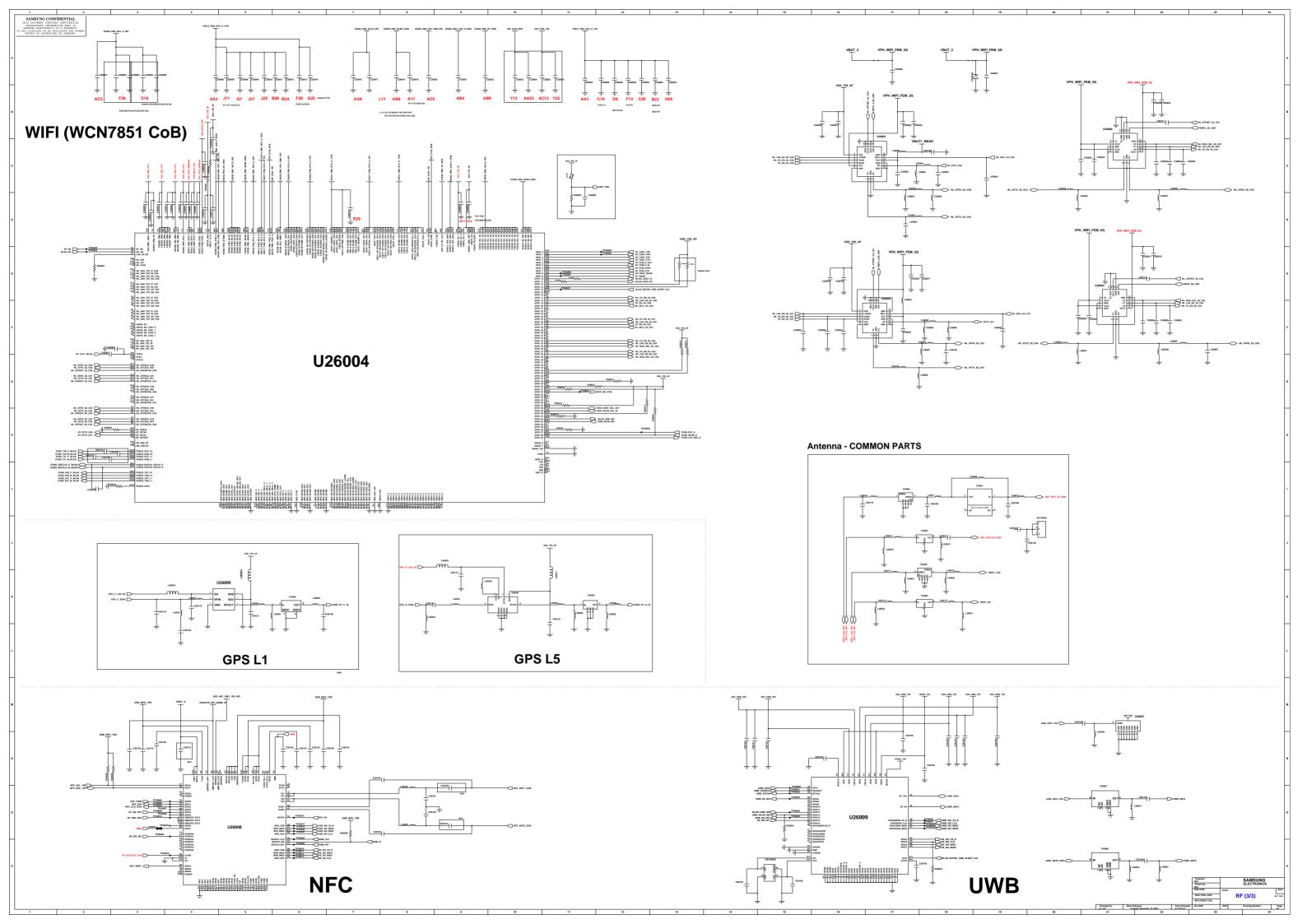
**System** 

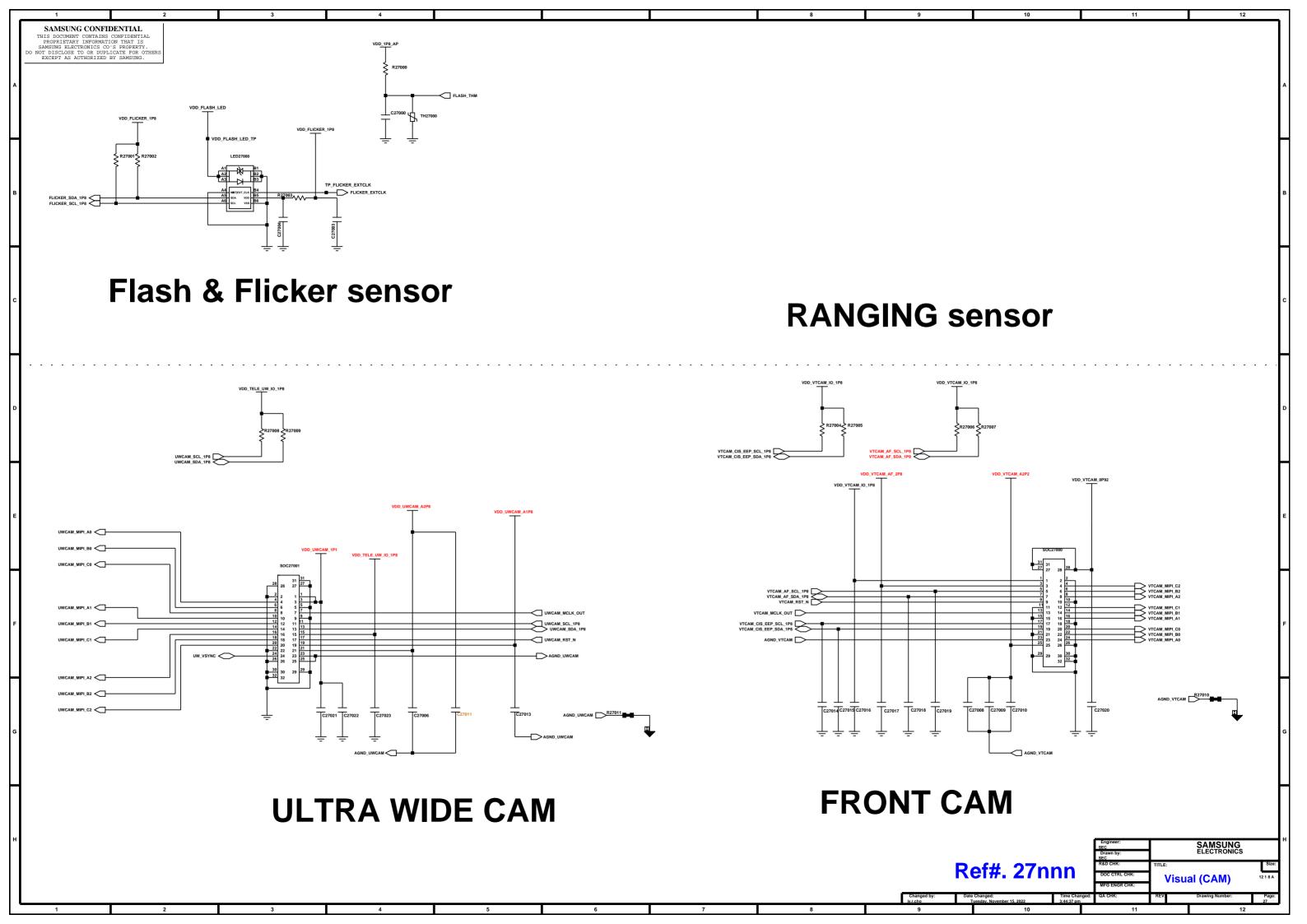


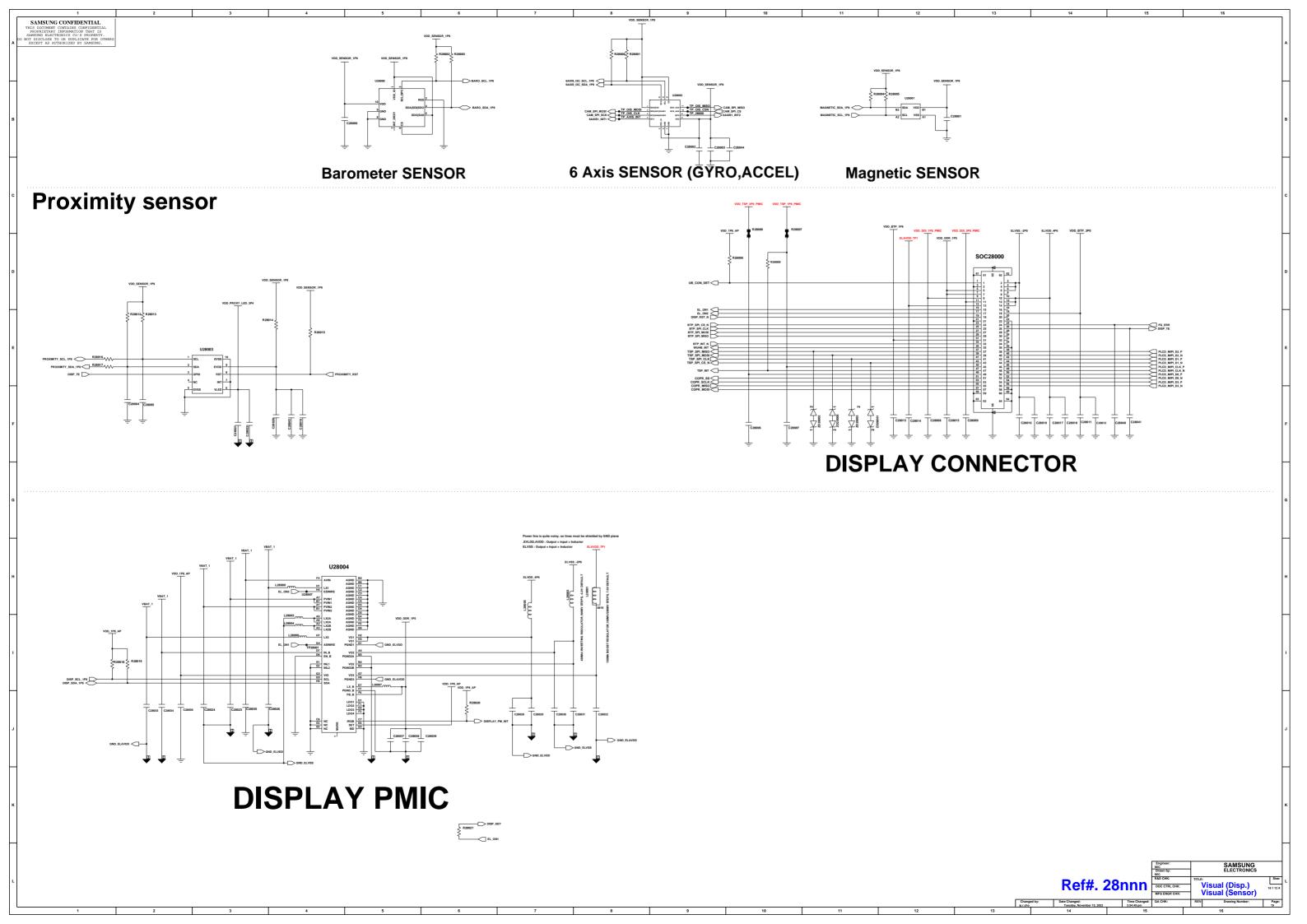






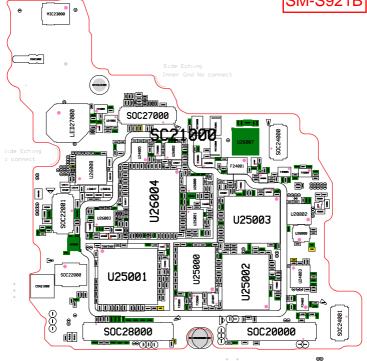


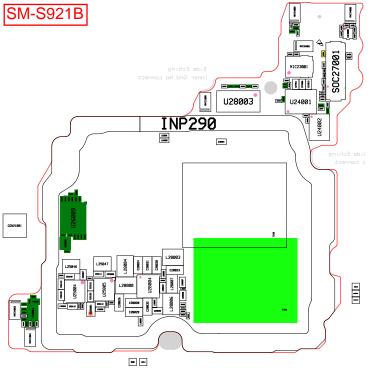




INTERPOSER Design **INP290** 

### SM-S921B





SM-S921B IFSUB PBA REV0.7

SM-S921B

sheet01: ANT
sheet02: LOGIC

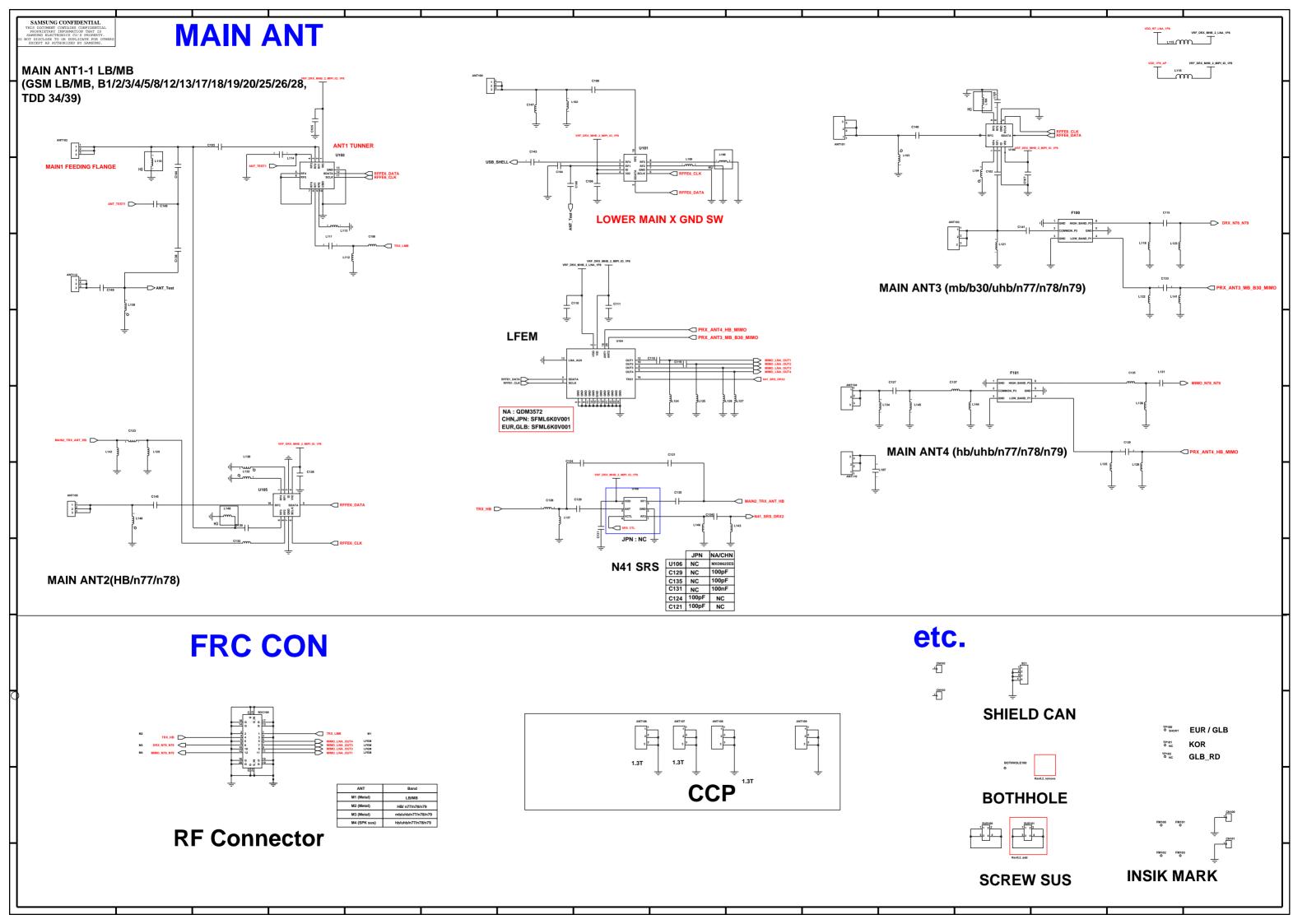
Engineer.

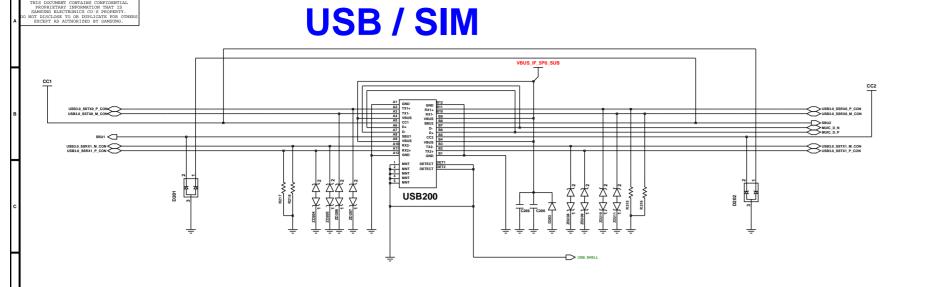
Disam by:

R&D DEK: TITLE:

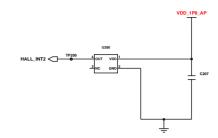
DOC OTRI, CHIK:

Page:





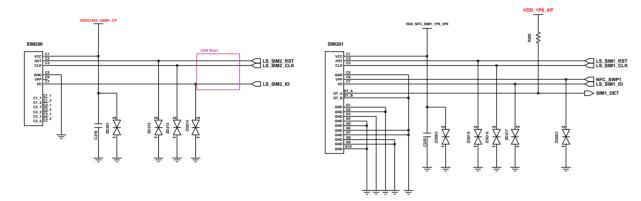
## **SENSOR**



HALL SENSOR

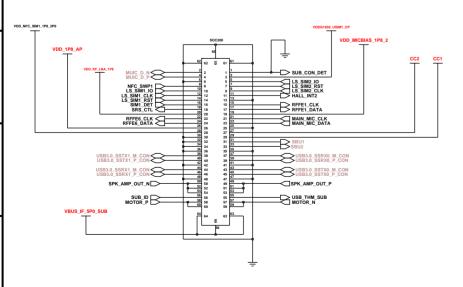
### **USB TYPE C CONNECTOR**

Deep Drawing



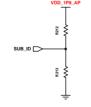
### **Stacked Dual SIM SOCKET**

# **BtoB CON**



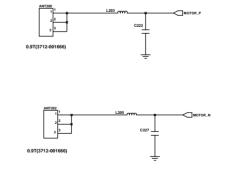
**SUB PCB IF CONNECTOR** 

### **SUB VERSION**

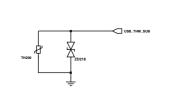


TYPICAL VALUE	ID_LSI	EXT_PU	EXT_PD	N.DM1
0	0	NC	332K, 1%	EUR_Sub6 Global_Sub6
480	1	332K, 1%	120K, 1%	NA_mmW NA_CAN_Sub6
720	2	270K, 1%	180K, 1%	CHN_Sub6
1080	3	180K, 1%	270K, 1%	KOR_Sub6_RD
1320	4	120K, 1%	332K, 1%	JPN_mmW
1480	5	100K, 1%	470K, 1%	Global_Sub6_RD

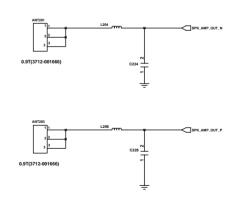
**AUDIO** 



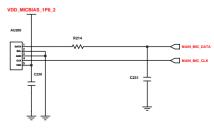




**USB/BATTERY THERMISTOR** 



**SPK CONTACT** 



**MAIN MIC** 

